

## aCCcess project launched: Europe's Chips Competence Centres connect for a stronger semiconductor future

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The Chips Competence Centres (CCC) planned under the EU Chips Act aim to take Europe's semiconductor expertise to the next level. But for the 27 centres in 25 European countries to not only coexist but also collectively advance the European industry, strong structures and smart networking are essential – this is where aCCcess comes in.

Launched in March 2025, this four-year EU project is building the **European Network of Chips Competence Centres (ENCCC)** and ensuring maximum synergies between CCCs, Chips Pilot Lines (PLs), and the virtual Design Platform (DP). Under the leadership of experienced cluster organisations and technology partners, a central platform is being created to accelerate innovation, provide businesses with easier access to technology and funding, and enhance Europe's semiconductor expertise on a global scale.

The CCCs, PLs, and the DP are key initiatives under the EU Chips Act catalyzed by the Chips JU. These initiatives provide companies – especially SMEs and start-ups – with essential resources, training, and access to cutting-edge semiconductor infrastructure. While CCCs focus on innovation and specialised expertise, CPLs bridge the gap between research and production, and the DP offers a cloud-based environment with advanced design tools to support chip development across Europe.

### aCCcess as the connecting link between CCCs, PLs, and DP

aCCcess aims to build and strengthen the European Network of Chips Competence Centres (ENCCC). To achieve this, the ENCCC is organised into five focus groups: Operations and Best Practices, Outreach and Events, Common Technology Offers, Training and Skills Development, and Finance. These groups will develop harmonised practices in these key areas, ensuring seamless collaboration across Europe.

aCCcess will support the development of CCCs, PLs, and DP through online and in-person events, including an annual community event to foster cross-border cooperation.

To simplify access to CCC services, training, and technology offers, aCCcess will create a **shared online marketplace** presenting CCC service catalogues with AI-supported maintenance and matchmaking opportunities. Additionally, the project will promote investment opportunities through a venture capital network and the Chips Finance Lab. A yearly pitching event for start-ups, which will highlight these funding opportunities.

Furthermore, aCCcess will establish a dedicated think tank and host monthly webinars with industry experts to discuss trends, foster public-private partnerships, and promote best practices in cluster management and operations. Lastly, pilot lines and the Design Platform will offer specialised training sessions and webinars to help CCCs enhance their resource offerings and visibility.



## **Key benefits of the project at a glance**

### **Strengthening competences**

- Access to CCCs, PLs, and DPs
- Faster processes via the aCCcess marketplace
- Early access to new technologies and best practices

### **Fostering expert exchange**

- Establishment and management of the Chips Think Tank, highlighting expert knowledge within ENCCC
- Events for direct interaction with experts from CCCs, PLs, and DPs
- Direct networking with relevant stakeholders for exchange and collaboration

### **Providing funding opportunities**

- Connection to the Chips Finance Lab: training on funding products from the EIB, EIF, etc.
- Matchmaking with investors
- Direct access to capital providers for business growth and project funding
- Improved success rates for securing innovation funding

## **About CCCs, LPs and DP**

### **Chips Competence Centres (CCC): Innovation hubs for Europe's semiconductor industry**

The Chips Competence Centres will provide companies – especially SMEs and start-ups – with resources to develop semiconductor solutions. This includes support, training, and access to large infrastructure facilities established under the EU Chips Act, such as the Chips Pilot Lines and the Design Platform. Each centre will reflect and strengthen regional and national capabilities, focusing on one or more key technology areas.

#### **Chips Pilot Lines (PLs): Bridging the gap from research to production**

The pilot lines aim to support companies in process development, testing, experimentation, and small-scale production. This approach is designed to close the gap between laboratory research and industrial manufacturing. The pilot lines will focus on key areas such as sub-2 nm GAA process technology, FD-SOI technology at 10 nm and below, and heterogeneous integration.

#### **Design Platform (DP): The cloud-based future of chip design**

The Design Platform will be a cloud-based virtual environment accessible across the European Union. It will offer a wide range of design tools and resources, from IP libraries to Electronic Design Automation (EDA) tools, as well as support services. The platform will be open, non-discriminatory, and transparent, ensuring broad accessibility.

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### **Project partners**

- Blumorpho
- VDI/VDE Innovation + Technik GmbH
- Minalogic
- Silicon Saxony
- Silicon Alps
- Mesap
- Czech National Semiconductor Cluster

### **Associated partners**

- IMEC (Interuniversitair Micro-Electronica Centrum)
- Fraunhofer (Fraunhofer-Gesellschaft zur Förderung der angewandten Forschung e.V.)
- CEA (Commissariat A L'Energie Atomique Et Aux Energies Alternatives)
- FTMC (Valstybinis Moksliniu Tyrimu Institutas Fiziniu Ir Technologijos Mokslu Centras) (Center for Physical Sciences and Technology)
- PPTF (Polska Platforma Technologiczna Fotonik)
- UL (UNIVERZA V LJUBLJANI)
- AMETIC (Asociación Multisectorial De Empresas De La Electronica, Las Tecnologías De La Información Y La Comunicación, De Las Telecomunicaciones Y De Los Contenidos Digitales)
- INNOVA-IRV (Fundación Instituto Ricardo Valle de Innovación)
- EIS (Ettevotluse Ja Innovatsiooni Sihtasutus) (Estonian Business and Innovation Agency - Enterprise Estonia)
- HTNL (Vereniging High Tech NL)
- TAMLINK (Tuotekehitys Oy Tamlink)
- GAIA (Association of Applied Knowledge and Technology Industries in the Basque Country)
- AENEAS (Association for European NanoElectronics Activities)
- EPoSS (European Association on Smart Systems Integration)
- INSIDE (Industry Association)